Dual N-Channel 20-V (D-S) MOSFET with Schottky Diode

PRODUCT SUMMARY				
	V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)[a]	Q_g (Typ.)
Channel-1	20	0.0094 at V_{GS} = 10 V	14.1	9.6
		0.0125 at V_{GS} = 4.5 V	12.2	
Channel-2	20	0.008 at V_{GS} = 10 V	20	14.1
		0.0095 at V_{GS} = 4.5 V	18.9	

SCHOTTKY PRODUCT SUMMARY		
V_{DS} (V)	V_{SD} (V) Diode Forward Voltage	I_F (A)
20	0.55 V at 2.5 A	2

FEATURES

- TrenchFET® Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested

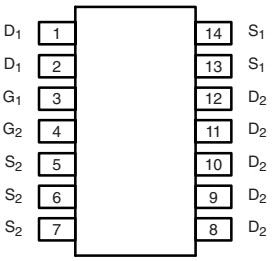
Pb-free

RoHS COMPLIANT

APPLICATIONS

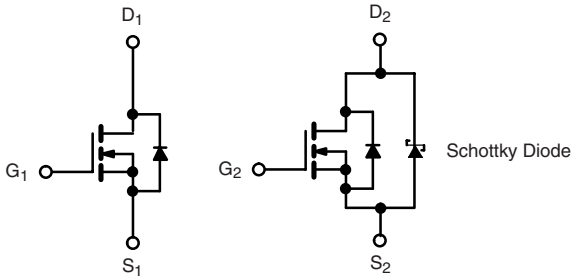
- DC/DC Converters
  - Game Stations
  - Notebook PC Logic

SO-14



Top View

Ordering Information: Si4340CDY-T1-E3 (Lead (Pb)-free)



ABSOLUTE MAXIMUM RATINGS T_A = 25 °C, unless otherwise noted					
Parameter		**Symbol**	**Channel-1**	**Channel-2**	**Unit**
Drain-Source Voltage		V_{DS}	20	20	V
Gate-Source Voltage		V_{GS}	± 20	± 16	
Continuous Drain Current (T_J = 150 °C)	T_C = 25 °C	I_D	14.1	20	A
	T_C = 70 °C		11.2	16.5	
	T_A = 25 °C		11.5[b, c]	15.2[b, c]	
	T_A = 70 °C		9.2[b, c]	12.2[b, c]	
Pulsed Drain Current		I_{DM}	40	50	
Source-Drain Current Diode Current	T_C = 25 °C	I_S	2.5	4.5	
	T_A = 25 °C		1.7[b, c]	2.5[b, c]	
Single Pulse Avalanche Current	L = 0.1 mH	I_{AS}	5		
Single Pulse Avalanche Energy		E_{AS}	1.25		mJ
Maximum Power Dissipation	T_C = 25 °C	P_D	3	5.4	W
	T_C = 70 °C		1.9	3.5	
	T_A = 25 °C		2[b, c]	3[b, c]	
	T_A = 70 °C		1.3[b, c]	1.9[b, c]	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 150		°C

THERMAL RESISTANCE RATINGS							
			Channel-1		**Channel-2**		
Parameter		**Symbol**	**Typ.**	**Max.**	**Typ.**	**Max.**	**Unit**
Maximum Junction-to-Ambient[b, d]	t ≤ 10 s	R_{thJA}	53	62.5	35	42	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	35	42	18	23	

Notes:
a. Based on T_C = 25 °C.
b. Surface Mounted on 1" x 1" FR4 board.
c. t = 10 s.
d. Maximum under Steady State conditions for channel 1 is 110 °C/W and channel 2 is 87 °C/W.

SPECIFICATIONS T_J = 25 °C, unless otherwise noted							
Parameter	**Symbol**	**Test Conditions**		**Min.**	**Typ.**	**Max.**	**Unit**
Static							
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0 V, I_D = 250 µA	Ch-1	20			V
		V_{GS} = 0 V, I_D = 250 µA	Ch-2	20			
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	I_D = 250 µA	Ch-1		20		mV/°C
		I_D = 25 mA	Ch-2		22		
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I_D = 250 µA	Ch-1		- 5.5		
		I_D = 25 mA	Ch-2		- 2.5		
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 µA	Ch-1	1		3	V
		V_{DS} = V_{GS}, I_D = 250 µA	Ch-2	0.8		2.2	
Gate-Body Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ± 20 V	Ch-1			100	nA
		V_{DS} = 0 V, V_{GS} = ± 16 V	Ch-2			100	
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 20 V, V_{GS} = 0 V	Ch-1			1	µA
		V_{DS} = 20 V, V_{GS} = 0 V	Ch-2			100	
		V_{DS} = 20 V, V_{GS} = 0 V, T_J = 85 °C	Ch-1			15	
		V_{DS} = 20 V, V_{GS} = 0 V, T_J = 85 °C	Ch-2			10 000	
On-State Drain Current[b]	$I_{D(on)}$	$V_{DS} \geq$ 5 V, V_{GS} = 10 V	Ch-1	20			A
		$V_{DS} \geq$ 5 V, V_{GS} = 10 V	Ch-2	30			
Drain-Source On-State Resistance[b]	$R_{DS(on)}$	V_{GS} = 10 V, I_D = 11.5 A	Ch-1		0.0077	0.0094	Ω
		V_{GS} = 10 V, I_D = 15.2 A	Ch-2		0.0065	0.008	
		V_{GS} = 4.5 V, I_D = 10 A	Ch-1		0.010	0.0125	
		V_{GS} = 4.5 V, I_D = 14 A	Ch-2		0.0075	0.0095	
Forward Transconductance[b]	g_{fs}	V_{DS} = 10 V, I_D = 11.5 A	Ch-1		45		S
		V_{DS} = 10 V, I_D = 15.2 A	Ch-2		73		
Dynamic[a]							
Input Capacitance	C_{iss}	Channel-1 V_{DS} = 10 V, V_{GS} = 0 V, f = 1 MHz	Ch-1		1300		pF
			Ch-2		1900		
Output Capacitance	C_{oss}		Ch-1		330		
		Channel-2 V_{DS} = 10 V, V_{GS} = 0 V, f = 1 MHz	Ch-2		500		
Reverse Transfer Capacitance	C_{rss}		Ch-1		150		
			Ch-2		160		
Total Gate Charge	Q_g	V_{DS} = 10 V, V_{GS} = 10 V, I_D = 11.5 A	Ch-1		21	32	nC
		V_{DS} = 10 V, V_{GS} = 10 V, I_D = 15.2 A	Ch-2		31	47	
		Channel-1 V_{DS} = 10 V, V_{GS} = 4.5 V, I_D = 11.5 A	Ch-1		9.6	15	
			Ch-2		14.1	22	
Gate-Source Charge	Q_{gs}	Channel-2 V_{DS} = 10 V, V_{GS} = 4.5 V, I_D = 15.2 A	Ch-1		4		
			Ch-2		5		
Gate-Drain Charge	Q_{gd}		Ch-1		3		
			Ch-2		3.5		
Gate Resistance	R_g	f = 1 MHz	Ch-1		0.65	1.2	Ω
			Ch-2		1.4	2.8	

Notes:

a. Guaranteed by design, not subject to production testing.

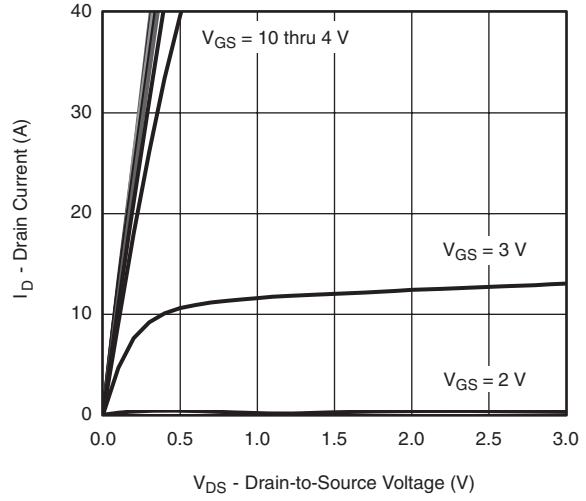
b. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.

SPECIFICATIONS T_J = 25 °C, unless otherwise noted							
Parameter	**Symbol**	**Test Conditions**		**Min.**	**Typ.**	**Max.**	**Unit**
Dynamic[a]							
Turn-On Delay Time	$t_{d(on)}$	Channel-1 V_{DD} = 10 V, R_L = 1.1 Ω $I_D \cong$ 9.2 A, V_{GEN} = 4.5 V, R_g = 1 Ω	Ch-1		20	30	ns
			Ch-2		22	35	
Rise Time	t_r		Ch-1		10	15	
			Ch-2		10	15	
Turn-Off Delay Time	$t_{d(off)}$	Channel-2 V_{DD} = 10 V, R_L = 1 Ω $I_D \cong$ 10 A, V_{GEN} = 4.5 V, R_g = 1 Ω	Ch-1		20	30	
			Ch-2		32	50	
Fall Time	t_f		Ch-1		10	15	
			Ch-2		10	15	
Turn-On Delay Time	$t_{d(on)}$	Channel-1 V_{DD} = 10 V, R_L = 1.1 Ω $I_D \cong$ 9.2 A, V_{GEN} = 10 V, R_g = 1 Ω	Ch-1		10	15	
			Ch-2		10	15	
Rise Time	t_r		Ch-1		10	15	
			Ch-2		10	15	
Turn-Off Delay Time	$t_{d(off)}$	Channel-2 V_{DD} = 10 V, R_L = 1 Ω $I_D \cong$ 10 A, V_{GEN} = 10 V, R_g = 1 Ω	Ch-1		20	30	
			Ch-2		25	40	
Fall Time	t_f		Ch-1		10	15	
			Ch-2		10	15	
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I_S	T_C = 25 °C	Ch-1			2.5	A
			Ch-2			4.5	
Pulse Diode Forward Current[a]	I_{SM}		Ch-1			40	
			Ch-2			50	
Body Diode Voltage	V_{SD}	I_S = 9.2 A	Ch-1		0.8	1.2	V
		I_S = 2.5 A	Ch-2		0.45	0.55	
Body Diode Reverse Recovery Time	t_{rr}	Channel-1 I_F = 9.2 A, di/dt = 100 A/µs, T_J = 25 °C Channel-2 I_F = 2.5 A, di/dt = 100 A/µs, T_J = 25 °C	Ch-1		30	60	ns
			Ch-2		30	60	
Body Diode Reverse Recovery Charge	Q_{rr}		Ch-1		15	25	nC
			Ch-2		20	30	
Reverse Recovery Fall Time	t_a		Ch-1		12		ns
			Ch-2		14		
Reverse Recovery Rise Time	t_b		Ch-1		18		
			Ch-2		16		

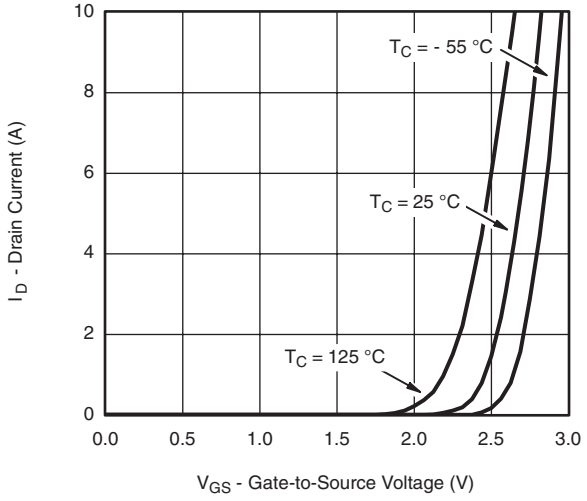
Notes:
a. Guaranteed by design, not subject to production testing.
b. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

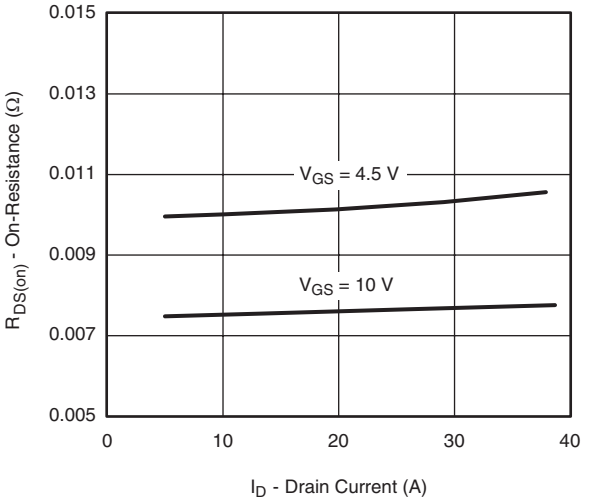
CHANNEL-1 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



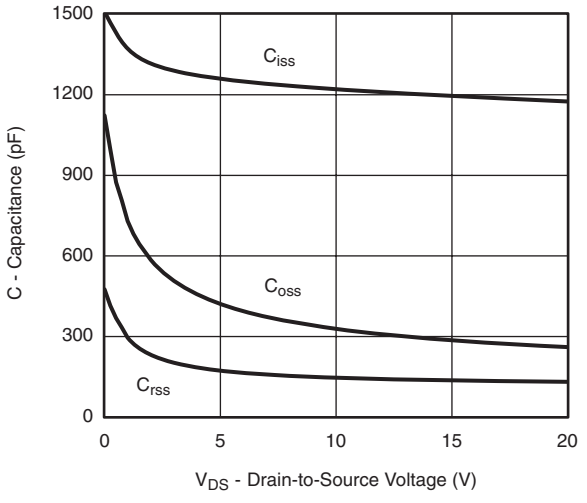
Output Characteristics



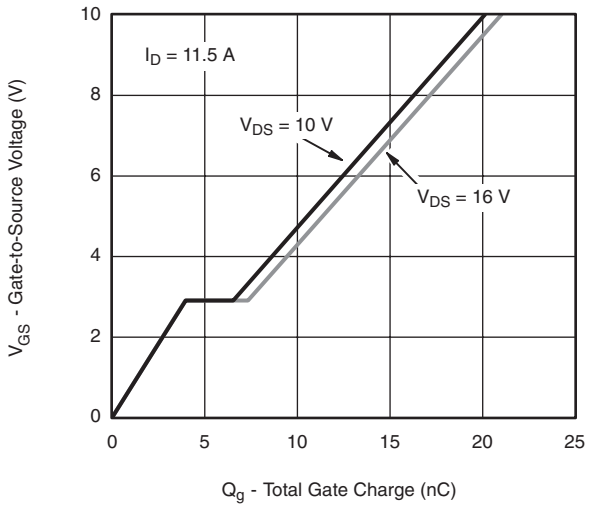
Transfer Characteristics



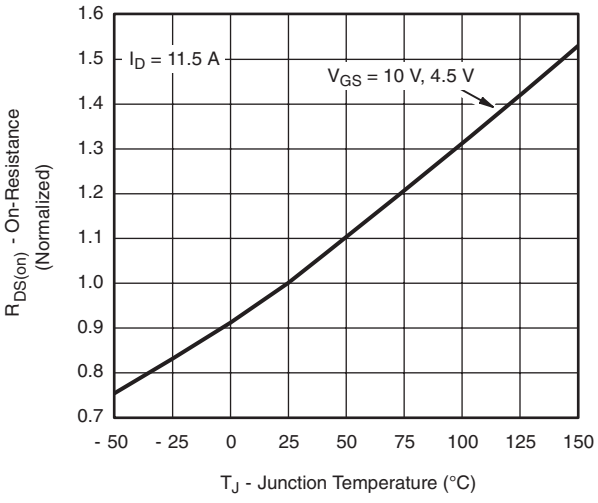
On-Resistance vs. Drain Current



Capacitance

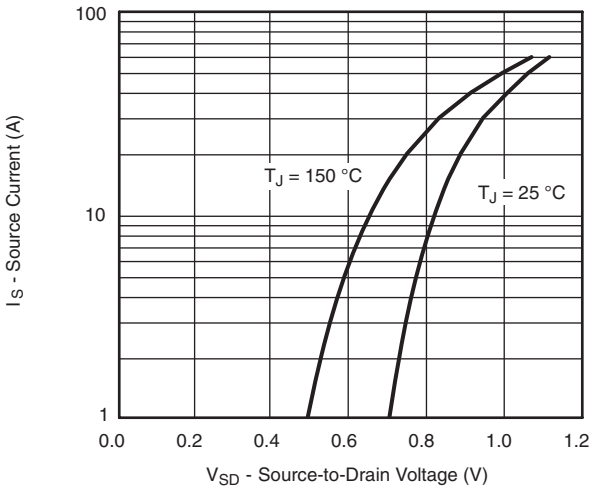


Gate Charge

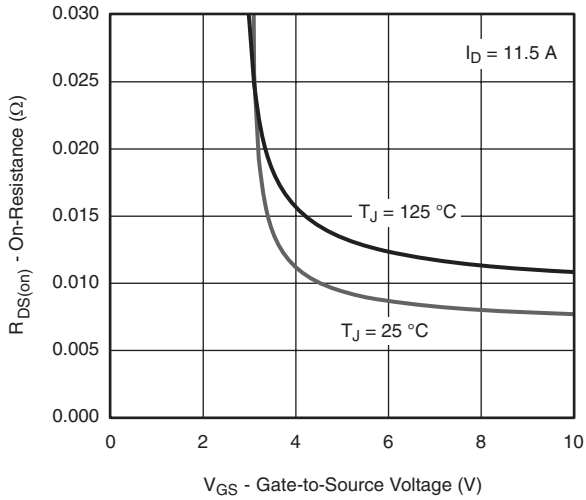


On-Resistance vs. Junction Temperature

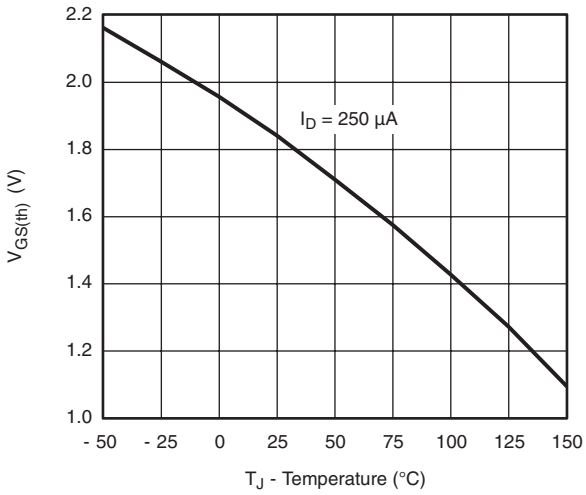
CHANNEL-1 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



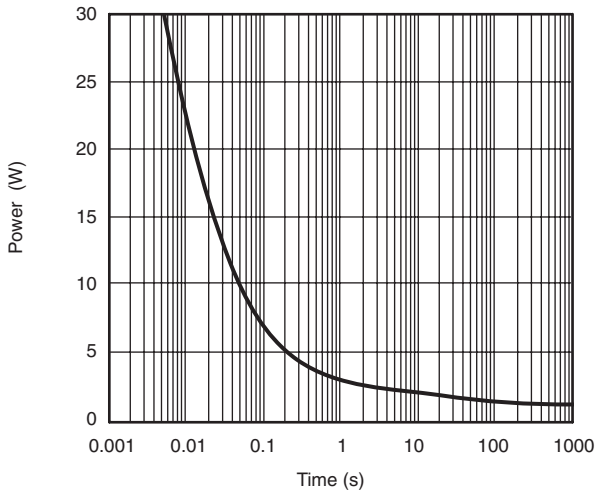
Source-Drain Diode Forward Voltage



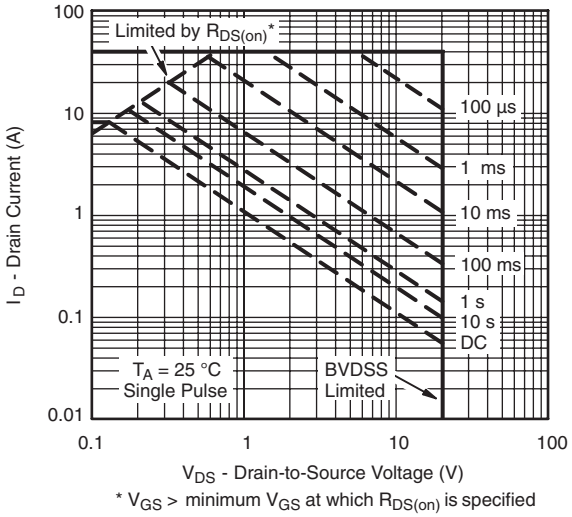
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



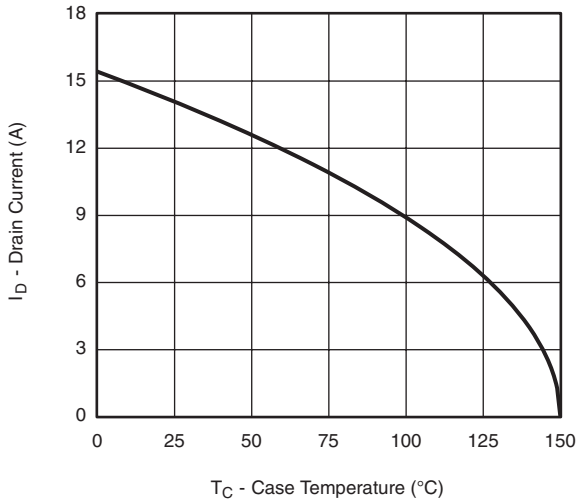
Single Pulse Power



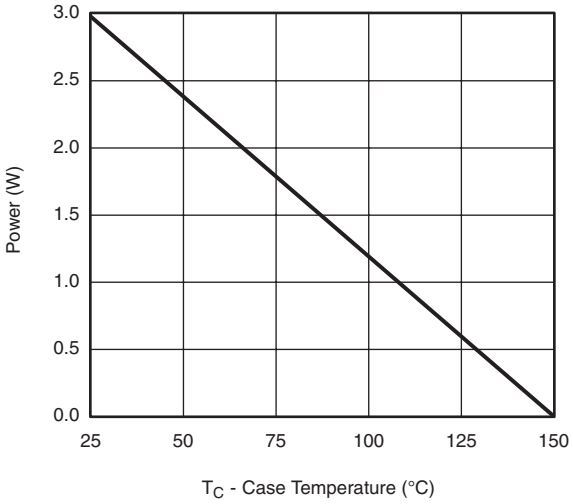
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

CHANNEL-1 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



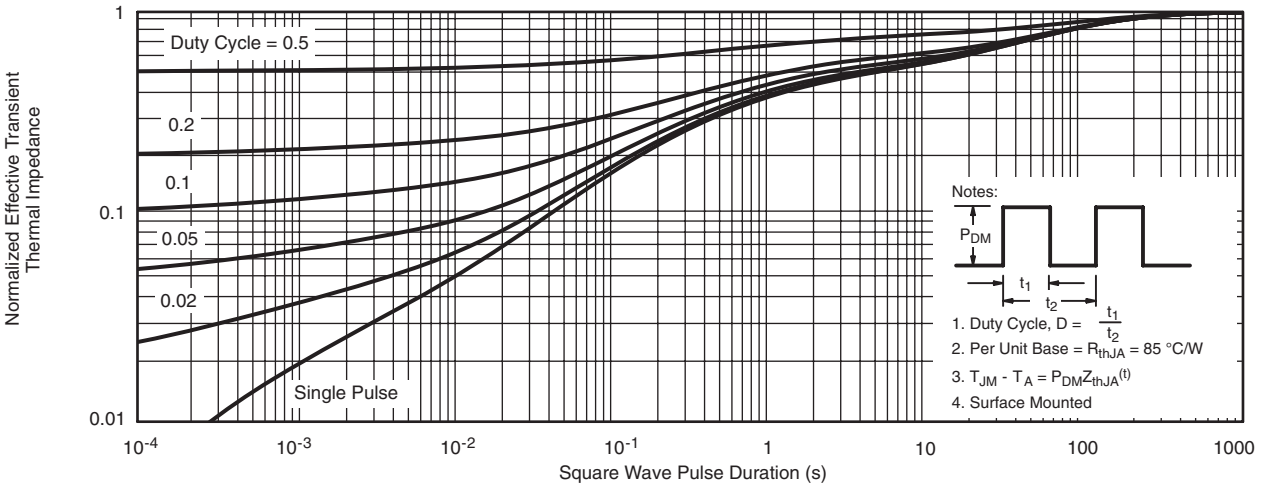
Current Derating*



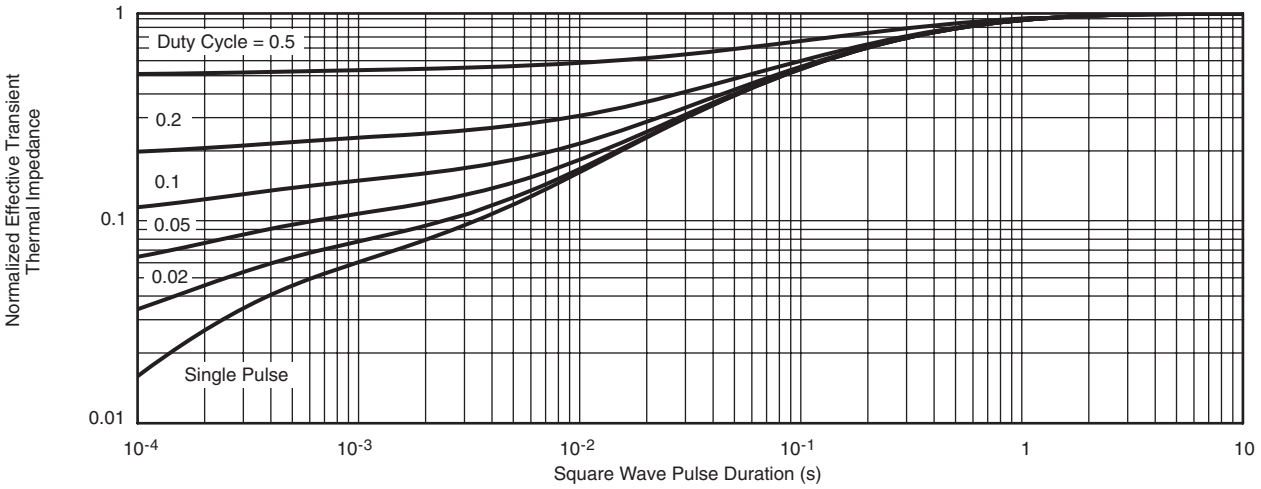
Power Derating

* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

CHANNEL-1 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

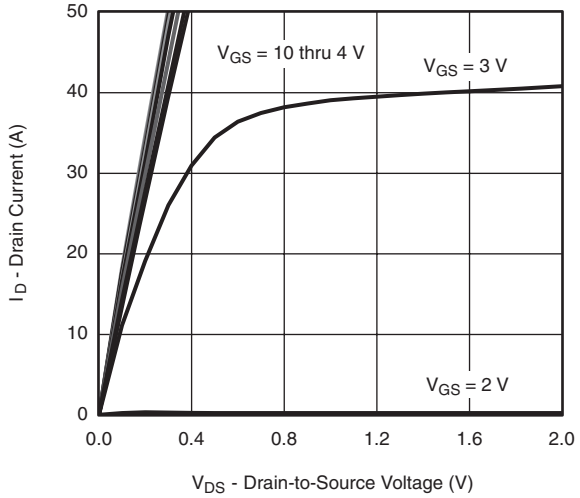


Normalized Thermal Transient Impedance, Junction-to-Ambient

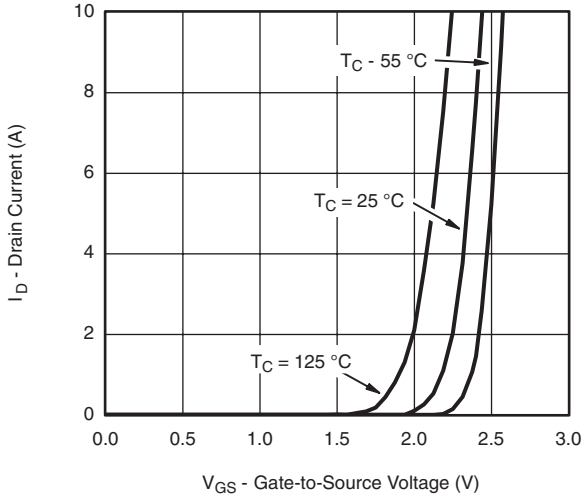


Normalized Thermal Transient Impedance, Junction-to-Foot

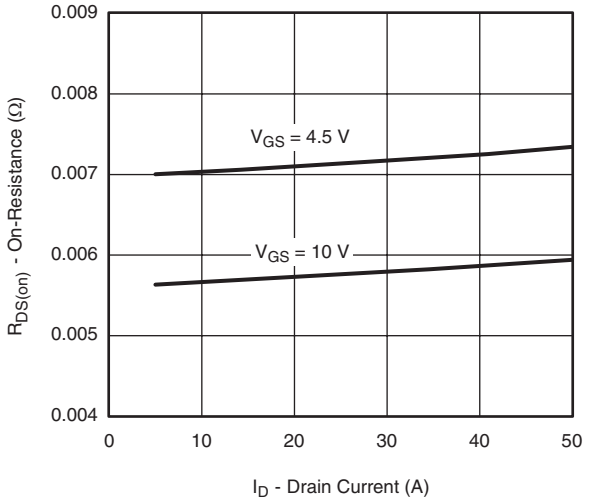
CHANNEL-2 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



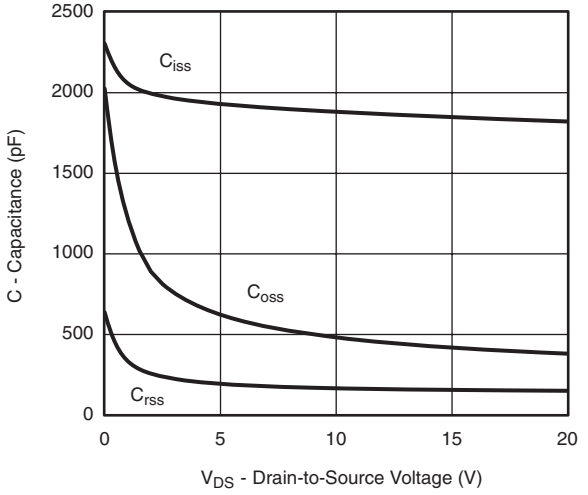
Output Characteristics



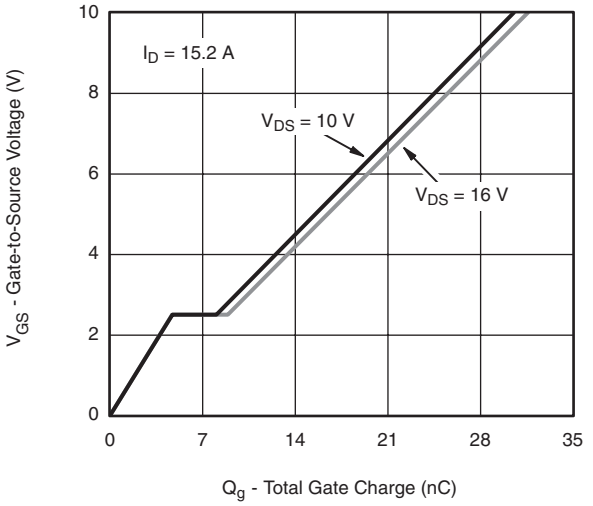
Transfer Characteristics



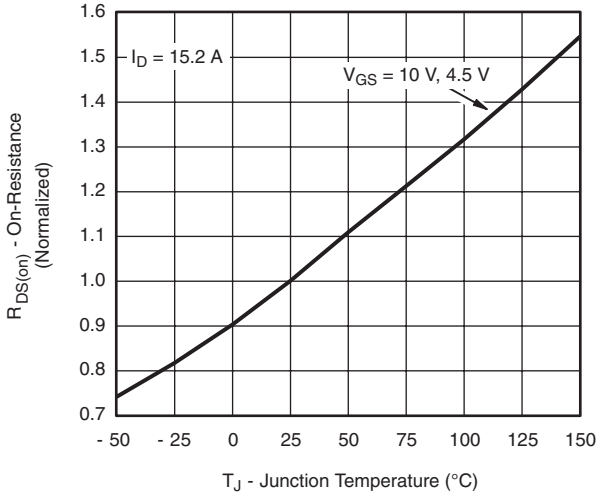
On-Resistance vs. Drain Current



Capacitance

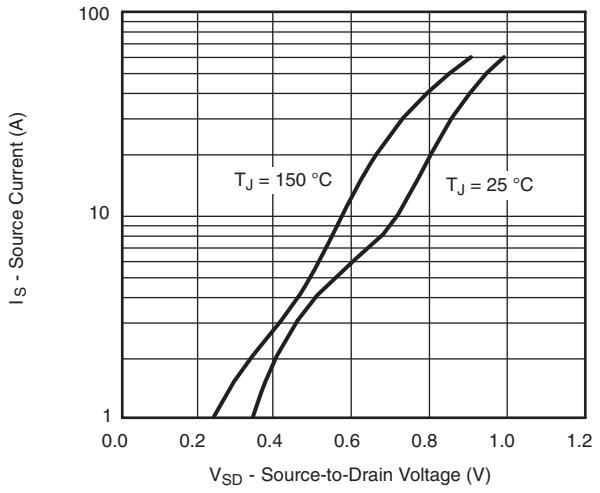


Gate Charge

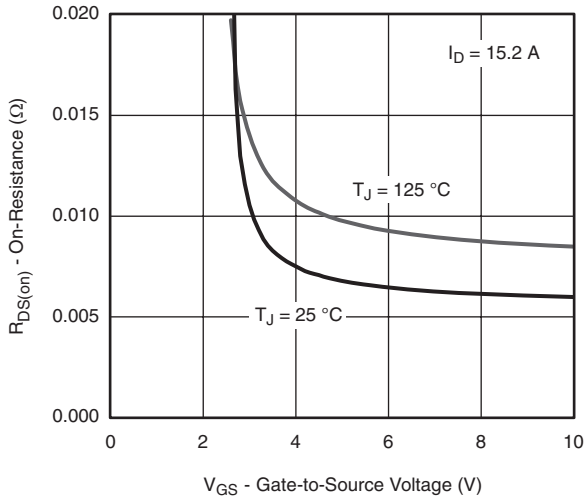


On-Resistance vs. Junction Temperature

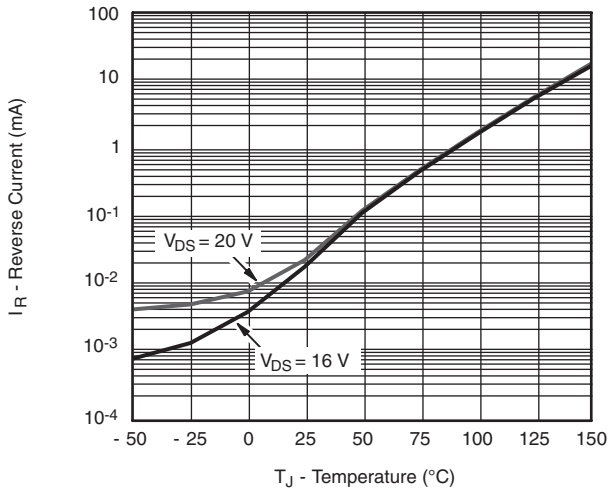
CHANNEL-2 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



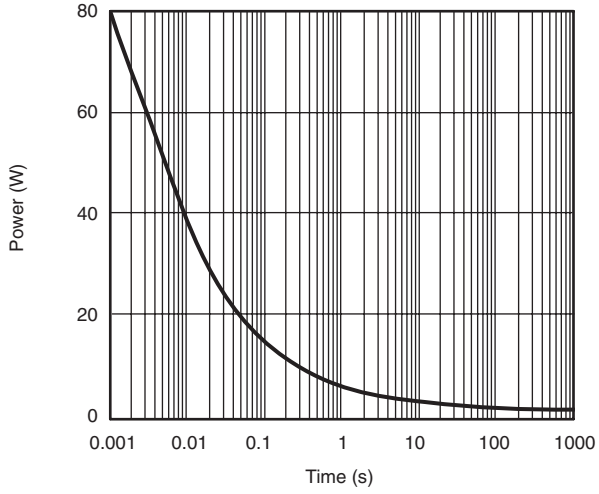
Source-Drain Diode Forward Voltage



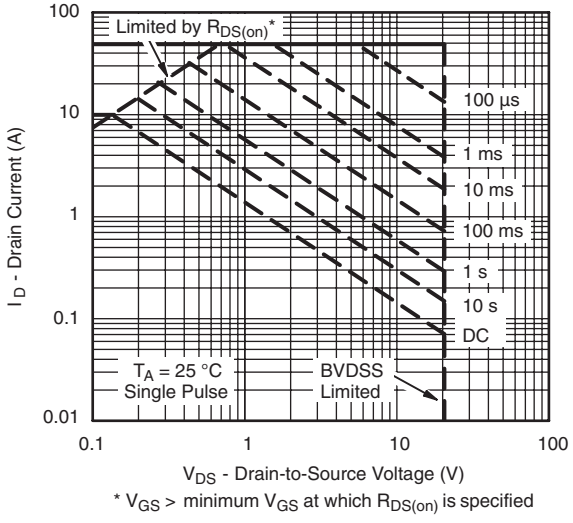
On-Resistance vs. Gate-to-Source Voltage



Reverse Current vs. Junction Temperature



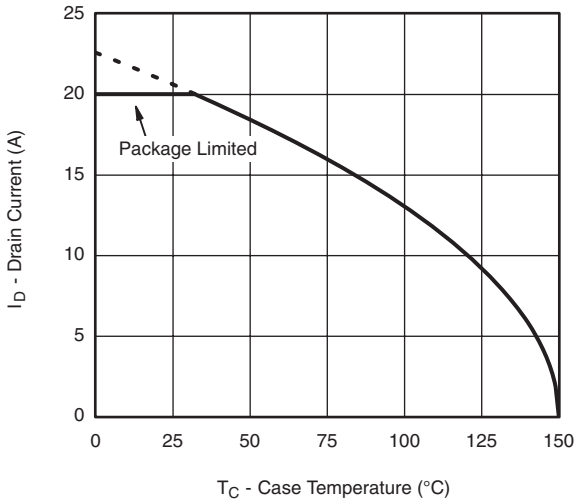
Single Pulse Power



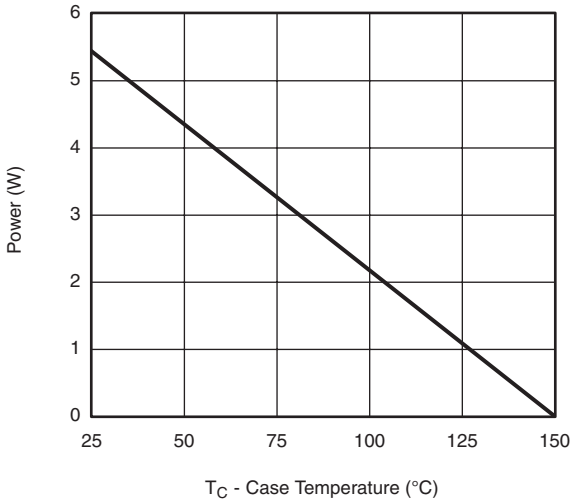
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

CHANNEL-2 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



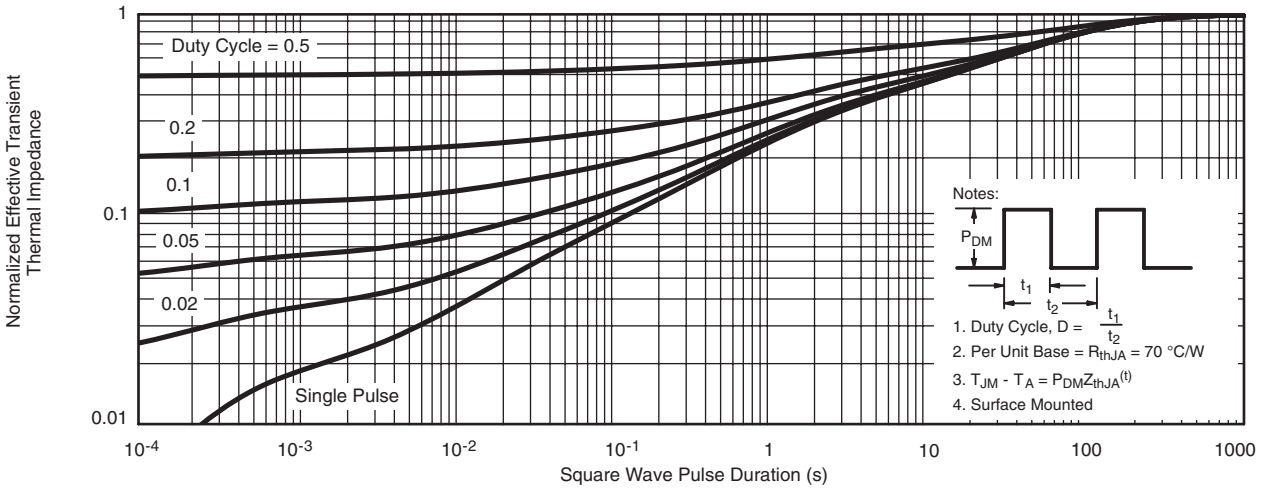
Current Derating*



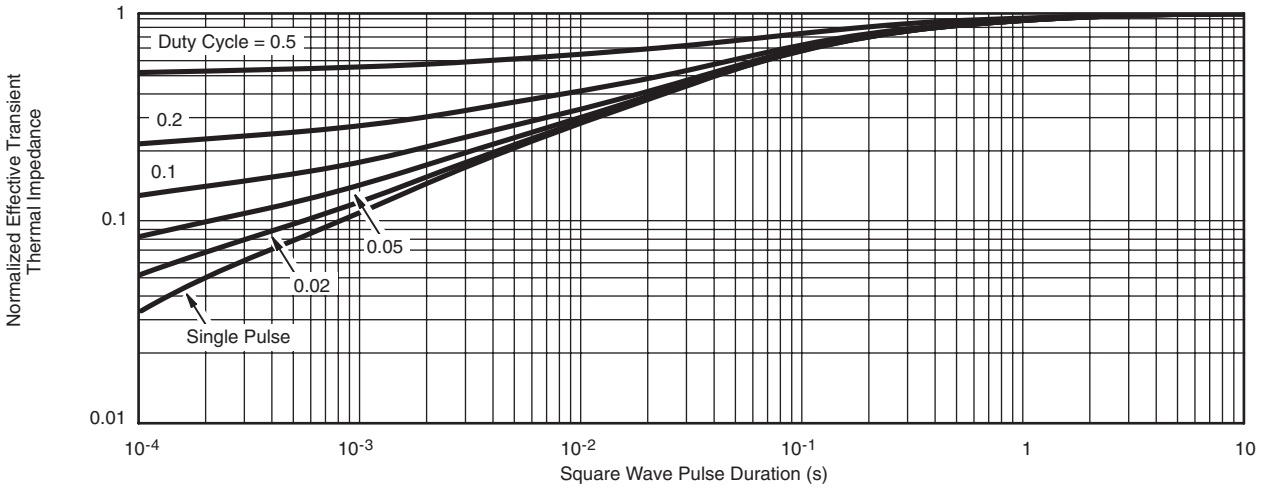
Power Derating

* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

CHANNEL-2 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?68398.

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